

FORM PTO-1390
(REV 11-98)

U S DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTORNEY'S DOCKET NUMBER

FILED: March 16, 2000
500.38296X00**TRANSMITTAL LETTER TO THE UNITED STATES
DESIGNATED/ELECTED OFFICE (DO/EO/US)
CONCERNING A FILING UNDER 35 U.S.C. 371**

U S APPLICATION NO (If known see 37 CFR 1.5)

09/508771

INTERNATIONAL APPLICATION NO.

PCT/JP98/04184

INTERNATIONAL FILING DATE

17 September 1998 (17.09.98)

PRIORITY DATE CLAIMED

19 September 1997 (19.09.97)

TITLE OF INVENTION
PHOTOSENSITIVE FILM

APPLICANT(S) FOR DO/EO/US

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Applicant herewith submits to the United States Designated/Elected Office (DO/EO/US) the following items and other information:

1. ☒ This is a **FIRST** submission of items concerning a filing under 35 U.S.C. 371.
2. ☐ This is a **SECOND** or **SUBSEQUENT** submission of items concerning a filing under 35 U.S.C. 371.
3. ☐ This express request to begin national examination procedures (35 U.S.C. 371(f)) at any time rather than delay examination until the expiration of the applicable time limit set in 35 U.S.C. 371(b) and PCT Articles 22 and 39(1).
4. ☐ A proper Demand for International Preliminary Examination was made by the 19th month from the earliest claimed priority date.
5. ☒ A copy of the International Application as filed (35 U.S.C. 371(c)(2))
 - a. ☐ is transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☒ has been transmitted by the International Bureau.
 - c. ☐ is not required, as the application was filed in the United States Receiving Office (RO/US).
6. ☒ A translation of the International Application into English (35 U.S.C. 371(c)(2)).
7. ☐ Amendments to the claims of the International Application under PCT Article 19 (35 U.S.C. 371(c)(3))
 - a. ☐ are transmitted herewith (required only if not transmitted by the International Bureau).
 - b. ☐ have been transmitted by the International Bureau.
 - c. ☐ have not been made; however, the time limit for making such amendments has NOT expired.
 - d. ☐ have not been made and will not be made.
8. ☐ A translation of the amendments to the claims under PCT Article 19 (35 U.S.C. 371(c)(3)).
9. ☒ An oath or declaration of the inventor(s) (35 U.S.C. 371(c)(4)).
10. ☐ A translation of the annexes to the International Preliminary Examination Report under PCT Article 36 (35 U.S.C. 371(c)(5)).

Items 11. to 16. below concern document(s) or information included:

11. ☐ An Information Disclosure Statement under 37 CFR 1.97 and 1.98.
12. ☒ An assignment document for recording. A separate cover sheet in compliance with 37 CFR 3.28 and 3.31 is included.
13. ☐ A **FIRST** preliminary amendment.
☐ A **SECOND** or **SUBSEQUENT** preliminary amendment.
14. ☐ A substitute specification.
15. ☒ A change of power of attorney and/or address letter.
16. ☒ Other items or information:

INTERNATIONAL PUBLICATION NO. WO 99/15936
INTERNATIONAL SEARCH REPORT
INFORMATION DISCLOSURE SHEET UNDER 37 CFR 1.56 WITH ATTACHED REFERENCES
FIGURES 1A-1B

U.S. APPLICATION NO. (if known see 37 CFR 1.5)

09/508771

INTERNATIONAL APPLICATION NO
PCT/JP98/04184ATTORNEY'S DOCKET NUMBER
500.38296X0017. ☒ The following fees are submitted:**BASIC NATIONAL FEE (37 CFR 1.492 (a) (1) - (5))**

Neither international preliminary examination fee (37 CFR 1.482)
nor international search fee (37 CFR 1.445(a)(2)) paid to USPTO
and International Search Report not prepared by the EPO or JPO \$970.00

International preliminary examination fee (37 CFR 1.482) not paid to
USPTO but International Search Report prepared by the EPO or JPO \$840.00

International preliminary examination fee (37 CFR 1.482) not paid to USPTO but
international search fee (37 CFR 1.445(a)(2)) paid to USPTO \$760.00

International preliminary examination fee paid to USPTO (37 CFR 1.482)
but all claims did not satisfy provisions of PCT Article 33(1)-(4) \$670.00

International preliminary examination fee paid to USPTO (37 CFR 1.482)
and all claims satisfied provisions of PCT Article 33(1)-(4) \$96.00

ENTER APPROPRIATE BASIC FEE AMOUNT =**CALCULATIONS PTO USE ONLY**

\$ 840.00

Surcharge of \$130.00 for furnishing the oath or declaration later than ☐ 20 ☐ 30
months from the earliest claimed priority date (37 CFR 1.492(c)).

\$

CLAIMS	NUMBER FILED	NUMBER EXTRA	RATE
Total claims	8 -20 =	0	X \$18.00
Independent claims	1 -3 =	0	X \$78.00

\$ 0.00

Multiple dependent claim(s) (if applicable)	+ \$260.00
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\$ 0.00

TOTAL OF ABOVE CALCULATIONS =

\$ 840.00

Reduction of 1/2 for filing by small entity, if applicable. A Small Entity Statement
must also be filed (Note 37 CFR 1.9, 1.27, 1.28).

\$ 0.00

SUBTOTAL =

\$ 840.00

Processing fee of \$130.00 for furnishing the English translation later than ☐ 20 ☐ 30
months from the earliest claimed priority date (37 CFR 1.492(f)).

\$

TOTAL NATIONAL FEE =

\$ 840.00

Fee for recording the enclosed assignment (37 CFR 1.21(h)). The assignment must be
accompanied by an appropriate cover sheet (37 CFR 3.28, 3.31). \$40.00 per property

\$ 40.00

TOTAL FEES ENCLOSED =

\$ 880.00

Amount to be:
refunded

\$

charged

\$

a. ☒ A check in the amount of \$ 880.00 to cover the above fees is enclosed.

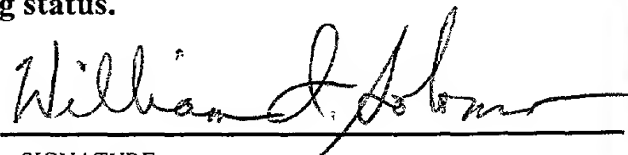
b. ☐ Please charge my Deposit Account No. _____ in the amount of \$ _____ to cover the above fees.
A duplicate copy of this sheet is enclosed.

c. ☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any
overpayment to Deposit Account No. 01-2135 A duplicate copy of this sheet is enclosed.

NOTE: Where an appropriate time limit under 37 CFR 1.494 or 1.495 has not been met, a petition to revive (37 CFR 1.137(a) or (b)) must be filed and granted to restore the application to pending status.

SEND ALL CORRESPONDENCE TO

William I. Solomon
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SIGNATURE

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NAME

28,565

REGISTRATION NUMBER

1/19/84

09/508771

428 Rec'd PCT/PTO

16 MAR 2000

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23/8

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DESCRIPTION

PHOTOSENSITIVE FILM

TECHNICAL FIELD

This invention relates to a photosensitive film successfully usable in metal etching fabrications of lead frame, metal mask, etc.

5 BACKGROUND ART

In the field of current semiconductor elements, there is a growing tendency of lessening the weight, decreasing the thickness, reducing the size of elements and manufacturing such elements in a small lot-high variety
10 manner. As a result of this tendency, the lead frame used for mounting IC chips on substrate is required to have an increased number of pins in a more slender and smaller size. On the other hand, the stamping process is unable to produce such small-sized articles satisfying the require-
15 ment of the miniaturization because of elevated cost of metallic die needed by the small lot-high variety production. Thus, the etching process is advantageous over the stamping process for the small lot-high variety production because it can produce small-sized articles
20 without using any metallic die. The etching process uses a photosensitive resin in either of the three forms, namely water-soluble photosensitive resin, solvent-containing liquid photosensitive resin and photosensitive film.

The use of liquid photosensitive resin has

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general faults in that an enormous investment must be made in the coating apparatus, the coating process requires considerably much labor, serviceable lives of the photosensitive resin itself and the coated film of photosensitive resin are short, and sensitivity is low. In addition, individual cases have their own faults. For instance, the water-soluble liquid photosensitive resin in which casein or PVA (polyvinyl alcohol) is cured with a chromic acid salt has a problem that a complicated step of waste water treatment must be provided for the disposal of harmful heavy metal salt after use. On the other hand, the solvent-containing liquid photosensitive resin has a problem that an organic solvent is discharged into the atmospheric air in the course of coating, which exercises an adverse influence upon environments.

On the other hand, the photosensitive film has a sandwich structure in which a photosensitive resin composition is coated on a transparent support film, dried and then covered with a protecting film. At the time of lamination, the protecting film is removed and at the same time the photosensitive resin layer is thermally press-bonded to the underlying metal to form an image. Accordingly, the photosensitive film is lower in the cost for equipments, higher in sensitivity and longer in the working life than the above-mentioned liquid photosensitive resins, and is superior in the suitability for metallic precision fabrications.

As the support film of the photosensitive film,

polyester films such as PET (polyethylene terephthalate) film are generally used. As the protecting film, polyolefin films such as PE (polyethylene) film are generally used. The protecting film is removed at the time of lamination. The polyolefin film conventionally used as a protecting film is produced by thermally melting and kneading a raw material and then forming it by extrusion, biaxial orientation or casting. In general, protecting films of polyolefin or the like include unmelted materials or thermally deteriorated regions called fish eyes. The fish eye usually has a diameter (ϕ) of 30 to 600 μm , forming a protrusion on the film surface up to a height of 2 to 40 μm . The convex portions of the fish eyes are transferred onto the photosensitive resin layer to form concavities on the photosensitive resin layer, so that air voids 6 are formed on the substrate after lamination as seen in Fig. 1B. That is to say, if a photosensitive film comprising a support film 1, a photosensitive resin layer 2 and a protecting film 3 carrying fish eyes 4 (see: Fig. 1A) is laminated, after releasing the protecting film 3 therefrom, onto a substrate 5, air voids appear as seen in Fig. 1B. Formation of the air voids has a relation with film thickness of the photosensitive resin layer so that a smaller film thickness of photosensitive resin layer causes a more ready formation of air voids. The presence of such air voids causes formation of defective pattern and breakage of wire in the subsequent steps of exposure, development and etching.

As a means for preventing such phenomena, JP-A 3-12402 discloses the use of a film having a flat and smooth surface as the releasable film at the time of lamination. The method of JP-A 3-12402, however, is characterized by coating a photosensitive resin composition onto a releasable film to be peeled off at the time of lamination and drying the coat to form a photosensitive resin layer, followed by laminating thereon a support film. The releasable film must be selected from materials showing no thermal dimensional change when it is coated with a photosensitive resin composition and dried. In other words, the materials usable for this purpose are restricted.

Apart from the above, the method of vacuum lamination is useful as mentioned in JP-A 52-66581, JP-A 51-63702, and JP-A 1-314144. This method, however, is disadvantageous in that it needs an apparatus of larger size as compared with the conventional normal pressure lamination method and it tends to generate dusts because inner atmosphere of lamination chamber is kept at a vacuum.

DISCLOSURE OF INVENTION

It is an object of this invention to provide a photosensitive film which can be laminated by the normal pressure lamination method on the surface of a substrate having a metallic surface in a high product yield, with formation of a reduced number of air voids, and in a high workability.

It is another object of this invention to provide a photosensitive film exercising the above-mentioned effect of the invention and further exhibiting excellent lamination characteristics.

5 It is yet another object of this invention to provide a photosensitive film exercising the above-mentioned effect of the invention and exhibiting a particularly high performance when used for metal etching fabrication of lead frame, metal mask, etc.

10 This invention provides a photosensitive film which comprises a support film (A), a photosensitive resin composition-containing photosensitive resin layer (B) formed on said support film (A), and a protecting film (C) stuck onto said photosensitive resin layer (B), wherein the
15 number of fish eyes having a diameter of at least 80 μm included in said protecting film (C) does not exceed 5 fish eyes/ m^2 and said photosensitive resin composition-containing photosensitive resin layer (B) has a film thickness of 5 to 30 μm .

20 BRIEF DESCRIPTION OF DRAWINGS

Fig. 1A and Fig. 1B are cross-sectional views illustrating the generation of air voids.

BEST MODE FOR CARRYING OUT THE INVENTION

The support film (A) used in this invention is,
25 for instance, a polyester film such as Tetoron Film GS Series manufactured by Teijin Ltd., Myler Film D Series

manufactured by E. I. Du Pont de Nemours and Co., and the like. Preferably, the support film (A) is a polyethylene terephthalate film. The support film (A) preferably has a film thickness of 12 to 25 μm . If thickness of the film (A) is smaller than 12 μm , mechanical strength of the support film is low and there is a tendency that the support film is broken in the coating process. If thickness of the support film (A) is greater than 25 μm , there is a tendency that the resolution is low and the price is high.

In this invention, the photosensitive resin composition used in the photosensitive resin composition-containing photosensitive resin layer (B) is not particularly limited, so far as the composition has a photosensitivity. Preferably used compositions are those comprising:

- (a) a binder polymer obtained by copolymerizing acrylic acid or methacrylic acid and alkyl esters thereof as constituent monomers,
- (b) a monomer having at least one polymerizable ethylenically unsaturated group in the molecule thereof, and
- (c) a photopolymerization initiator.

The binder polymer (a) may be any of a single binder polymer and a combination of two or more binder polymers.

As the alkyl ester of acrylic acid, for instance, methyl acrylate, ethyl acrylate, butyl acrylate,

2-ethylhexyl acrylate and the like can be referred to. These compounds may be used either singly or in combination of two or more compounds.

As the alkyl ester of methacrylic acid, for instance, methyl methacrylate, ethyl methacrylate, butyl methacrylate, 2-ethylhexyl methacrylate and the like can be referred to. These compounds may be used either singly or in combination of two or more compounds.

The acrylic acid and methacrylic acid mentioned above may be used in combination, if desired.

As the constituent monomer of the binder polymer, not only the acrylic acid, methacrylic acid and alkyl esters thereof but also vinyl monomers copolymerizable therewith can be used. As the vinyl monomers which are other than the acrylic acid, methacrylic acid and alkyl esters thereof and copolymerizable therewith, for instance, tetrahydrofurfuryl acrylate, tetrahydrofurfuryl methacrylate, dimethylaminomethyl acrylate, dimethylaminomethyl methacrylate, glycidyl acrylate, glycidyl methacrylate, 2,2,3,3-tetrafluoropropyl acrylate, 2,2,3,3-tetrafluoropropyl methacrylate, acrylamide, diacetoacrylamide, styrene, vinyltoluene and the like can be referred to. These monomers can be used either singly or in combination of two or more monomers.

The copolymer can be synthesized by mixing together the above-mentioned components and subjecting the mixture to a known polymerization process such as solution polymerization process.

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The compounding ratio of the above-mentioned constituent monomers is not particularly limited, but the monomers may be compounded at an arbitrary ratio. However, it is preferable from the viewpoint of the balance between alkali-developability and alkali-resistance to adjust the carboxyl group-content of component (a), namely the ratio of carboxyl group-containing monomers to the total monomers used, to 12 to 40% by weight.

The copolymers thus formed may be used either singly or in combination of two or more copolymers.

In this invention, the weight-average molecular weight, measured by gel permeation chromatography and calculated by referring to a standard polystyrene calibration curve, of the binder polymer (a) in the photosensitive resin composition-containing photosensitive resin layer (B) is not particularly limited. However, from the viewpoint of the balance between mechanical strength and alkali-developability, the weight-average molecular weight of binder polymer (a) is preferably in the range of from 20,000 to 300,000 and further preferably in the range of from 40,000 to 200,000. If the weight-average molecular weight is lower than 20,000, mechanical strength tends to be low. If the weight average molecular weight is higher than 300,000, alkali-developability tends to be inferior.

As the monomer (b) having at least one polymerizable ethylenically unsaturated group in the molecule thereof used in the photosensitive resin composition-containing photosensitive resin layer (B) of this

invention, for instance, there can be referred to the compounds obtained by reacting a polyhydric alcohol with an α,β -unsaturated carboxylic acid such as polyethylene glycol diacrylate having 2 to 14 ethylene units, trimethylolpropane diacrylate, trimethylolpropane triacrylate, tetramethylolmethane triacrylate, tetramethylolmethane tetraacrylate, polypropylene glycol diacrylate having 2 to 14 propylene units, dipentaerythritol pentaacrylate, dipentaerythritol hexaacrylate and the like; bisphenol A polyoxyalkylene diacrylates such as 2,2-bis(4-(acryloxydiethoxy)phenyl)propane, 2,2-bis(4-(acryloxypentaethoxy)phenyl)propane, 2,2-bis(4-acryloxydiisopropoxytriethoxy)phenyl)propane, and the like; compounds obtained by adding an α,β -unsaturated carboxylic acid to a glycidyl group-containing compound such as trimethylolpropane triglycidyl ether triacrylate, bisphenol A diglycidyl ether diacrylate and the like; and alkyl esters of acrylic acid such as methyl acrylate, ethyl acrylate, butyl acrylate, 2-ethylhexyl acrylate and the like. The methacrylates and methacrylic esters corresponding to these compounds can also be referred to. These compounds can be used alone or as a mixture thereof. Among them, the bisphenol A polyoxyalkylene dimethacrylates are preferable from the viewpoint of sensitivity, resolution, adhesiveness and mechanical properties.

As the photopolymerization initiator (c) usable in the photosensitive resin composition-containing photosensitive resin layer (B) of this invention, for instance,

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there can be referred to aromatic ketones such as benzophenone, N,N'-tetramethyl-4,4'-diaminobenzophenone, N,N'-tetraethyl-4,4'-diaminobenzophenone, 4-methoxy-4'-dimethylaminobenzophenone, 2-ethylanthraquinone, phenanthrenequinone and the like; benzoin ethers such as benzoin methyl ether, benzoin ethyl ether, benzoin phenyl ether and the like; benzoin derivatives such as benzoin methyl ketal and the like; 2,4,5-triarylimidazole dimers such as 2-(o-chlorophenyl)-4,5-diphenylimidazole dimer, 2-(o-chlorophenyl)-4,5-di(m-methoxyphenyl)-imidazole dimer, 2-(o-fluorophenyl)-4,5-diphenylimidazole dimer, 2-(o-methylphenyl)-4,5-diphenylimidazole dimer, 2-(p-methoxyphenyl)-4,5-diphenylimidazole dimer, 2,4-di(p-methoxyphenyl)-5-phenylimidazole dimer, 2-(2,4-dimethoxyphenyl)-4,5-diphenylimidazole dimer, 2-(p-methylmercaptophenyl)-4,5-diphenylimidazole dimer and the like; acridine derivatives such as 9-phenylacridine, 1,7-bis(9,9'-acridinyl)-heptane and the like; phenanthrenequinones such as 9,10-phenanthrenequinone and the like, etc. Among them, the 2,4,5-triarylimidazole dimers are preferable from the viewpoint of sensitivity and resolution. These photopolymerization initiators may be used either singly or in combination of two or more compounds.

In the photosensitive resin composition comprising the above-mentioned components (a), (b) and (c), the amount of component (a) is preferably in the range of from 40 to 80 parts by weight per 100 parts by weight of the sum

of components (a) and (b). If the amount of component (a) is less than 40 parts by weight, the photo-cured product tends to be brittle with inferior coating characteristics. If the amount of component (a) exceeds 80 parts by weight, sensitivity tends to be insufficient.

In the photosensitive resin composition comprising components (a), (b) and (c), the amount of component (b) is preferably in the range of from 20 to 60 parts by weight per 100 parts by weight of the sum of components (a) and (b). If the amount of component (b) is less than 20 parts by weight, sensitivity tends to be insufficient. If the amount of component (b) exceeds 60 parts by weight, the photo-cured product tends to be brittle.

In the photosensitive resin composition comprising components (a), (b) and (c), the amount of component (c) is preferably in the range of from 0.1 to 20 parts by weight per 100 parts by weight of the sum of components (a) and (b). If the amount of component (c) is less than 0.1 part by weight, sensitivity tends to be insufficient. If the amount of component (c) exceeds 20 parts by weight, there is a tendency that an increasing quantity of light tends to be absorbed at the surface of composition at the time of exposure, which brings about an insufficient photocure in the internal regions of the composition.

Into the photosensitive resin composition used in this invention may be incorporated, if necessary, a plasticizer, a thermal polymerization inhibitor, a color-

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developer such as leuco-Crystal Violet, tribromomethyl-phenyl sulfone and the like, a dye such as Malachite Green and the like, a pigment, a filler, an adhesiveness improver, a perfume, an imaging agent, etc.

5 The photosensitive resin composition comprising the components (a), (b) and (c) is formed into a photosensitive resin layer (B) by adding a solvent to the composition to prepare a solution, if necessary, and then coating the solution on a support film (A) and drying the
10 coat. Then, a protecting film (C) is stuck onto the photosensitive resin layer to prepare a photosensitive film.

 The solvent used for this purpose is not particularly limited, but all the known solvents can be
15 used. Examples of the solvent include acetone, methyl ethyl ketone, methyl isobutyl ketone, ethylene glycol monomethyl ether, ethylene glycol monoethyl ether, chloroform, methylene chloride, toluene, methanol, ethanol and the like. These solvents may be used either as a single
20 solvent or in combination of two or more solvents.

 Thickness of the photosensitive resin layer must be in the range of 5 to 30 μm . If the thickness is smaller than 5 μm , follow-up characteristics are deteriorated and defective pattern appears or breakage of wire occurs. If
25 the thickness is greater than 30 μm , resolution is deteriorated. Preferable thickness is 10 to 25 μm .

 Viscosity (at 30°C) of the photosensitive resin layer is preferably in the range of from 15 to 50 MPa·s,

and further preferably in the range of from 25 to 40 MPa·s. If the viscosity is lower than 15 MPa·s at 30°C, exudation of the resin, called "edge fusion", tends to occur readily. If the viscosity is higher than 50 MPa·s at 30°C, flow property of the resin is deteriorated which facilitates generation of micro-voids. The viscosity can be measured by the use of the following equation (I) expressing the behavior of a Newtonian fluid, namely by plotting t against $1/Z^4$ and measuring the slope of the line:

$$t = \eta \frac{3V^2}{8\pi F} \left(\frac{1}{Z^4} - \frac{1}{Z_0^4} \right) \quad (1)$$

wherein η is viscosity (Pa·s),

F is force applied in the direction of thickness (N),

V is volume of test piece (m^3),

Z is thickness (m), and

t is time (second).

The measurement can be practiced by means of TMA apparatus.

The number of fish eyes having a diameter (ϕ) of at least 80 μm included in the protecting film used in this invention must be $5/m^2$ or less. As used herein, the term "fish eye" means unmelted or deteriorated region of the raw material which has been taken into film at the time of thermally melting the raw material and forming it into a film by kneading, extrusion, stretching or casting.

Although the diameter of the fish eye varies depending on material, it is from about 10 μm to about 1

5 microscope. The diameter (ϕ) of fish eye means its maximum diameter.

10 Ra is from 0.01 to 0.03 μm . The surface roughness can be measured by means of contact type surface roughness meter.

15 in such a manner as filtering the raw material resin after thermal melting.

20 Paper Co., Ltd. and the like can also be referred to as examples of the protecting films preferably usable in this invention, though they are not limitative.

25 30 μm . If the thickness is smaller than 5 μm , such a film tends to be difficult to manufacture. If the thickness is larger than 50 μm , price of the film tends to be high.

It is preferable that adhesive strength between

the photosensitive resin composition-containing photosensitive resin layer (B) and the support film (A) is greater than adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the protecting film (C). If adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the support film (A) is smaller than adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the protecting film (C), there is a possibility that the photosensitive resin layer is transferred onto the protecting film upon removal of the protecting film at the time of lamination.

The photosensitive film of this invention can be successfully used as a photosensitive film for metal etching fabrications of lead frame, metal mask, etc.

Next, this invention is explained in more detail with reference to Examples. This invention is by no means limited by these Examples.

Examples 1-3 and Comparative Examples 1-2

A solution was prepared by mixing together the components (a), (b) and (c) shown in Table 1.

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Table 1

Material		Amount		
		Formulation		Formulation 3
		1	1'	
Component (a)	40% (by weight) solution of methacrylic acid/methyl methacrylate/butyl methacrylate/2-ethylhexyl acrylate copolymer (25/50/5/20 by weight) having a weight average molecular weight of 80,000 in 6/4 (by weight) mixture of methyl cellosolve and toluene	150 g (solid content 60 g)	160 g (solid content 64 g)	150 g (solid content 60 g)
Component (b)	2,2-Bis(4-methacryloxyphenyl)-propane (trade name BPE-500, manufactured by Shin-Nakamura Kagaku Kogyo K.K.)	40 g		40 g
Component (c)	Benzophenone N,N'-Tetraethyl-4,4-diaminobenzophenone 2-(o-chlorophenyl)-4,5-diphenylimidazole dimer	5 g 0.3 g 0 g		0 g 0.3 g 4 g
Other components	Color developer	1.0 g 1.0 g		0 g 1.0 g
	Dye	0.1 g		0.1 g
	Solvent	10 g 10 g 3 g		10 g 10 g 3 g

Next, the solution of photosensitive resin composition obtained above was uniformly coated onto a polyethylene terephthalate film having a thickness of 16 μm and dried for 5 minutes in a hot air circulation type oven kept at 100°C. Then, each of the protecting films shown in Table 2 were laminated thereon to obtain various photosensitive films. After dryness, thickness of the photosensitive resin layer was 15 μm .

The photosensitive films obtained above were superposed so that the photosensitive resin layers thereof came into mutual contact, to prepare a test piece having a thickness of 1 mm and a diameter of 7 mm. Using a IMA apparatus (Thermal Analysis TMA/SS100, manufactured by Seiko Denshi K. K.), a load of 2 to 40 g was applied to the test piece in the direction of thickness thereof at a temperature of 30 to 80°C, and the change in thickness was measured. Then, using the equation (I) relating to Newtonian fluid, t was plotted against $1/Z^4$. Slope of the line gave viscosity.

$$t = \eta \frac{3V^2}{8\pi F} \left(\frac{1}{Z^4} - \frac{1}{Z_0^4} \right) \quad (1)$$

On the other hand, a copper alloy plate having a thickness of 0.15 mm and a size of 20 × 20 cm square (trade name C-7025) manufactured by YAMAHA-OLIN METAL Co. was immersed in 3% (by weight) aqueous solution of sodium hydroxide at 50°C for one minute and then in a 1% (by volume) aqueous solution of hydrochloric acid at 25°C for

one minute, and then washed with water and dried to obtain a substrate. The photosensitive film obtained above was laminated on the substrate while removing the protecting film at a roll temperature of 110°C, under a pressure of 4 kg·f/cm², at a speed of 2 m/minute. The laminated substrate thus obtained was exposed to light by means of a 3 kW Super-High Pressure Mercury Lamp (HMW-201GX, manufactured by ORC Seisakusho, Ltd.) at 50 mJ/cm².

After the exposure, the number of air voids on the substrate was counted under a microscope at a multiplication of 100. Further, the size and number of fish eyes on each support film were measured under a microscope at a multiplication of 100.

The results are summarized in Table 2.

Table 2

No.	Protecting film		Number of fish eyes ($\phi \geq 80 \mu\text{m}$) (per m^2)	Formulation	Viscosity (Mpa · s)	Number of air voids generated (per m^2)	Removability of protecting film
	Kind	Film thickness (μm)					
Example 1	GS-16 (manufd. by Teijin, Ltd.)	16	0	1	40	0	○
				1'	55	5	○
				2	25	0	○
Example 2	PP-Type PT (manufd. by Shin-Etsu Film Co.)	25	0	1	40	0	◎
				1'	55	5	◎
				2	25	0	◎
Example 3	BO-2400 (manufd. by Toray Industries, Inc.)	25	0	1	40	0	◎
				1'	55	5	◎
Comparative Example 1	NF-13 (manufd. by Tamapoly Co.)	25	ca. 1,000	1	40	ca.900	◎
				2	25	ca.500	◎
Comparative Example 2	PP-Type R (manufd. by Shin-Etsu Film Co.)	25	ca. 1,200	1	40	ca.1,000	◎
				2	25	ca.1,000	◎
Example 4	E 200C (manufd. by Oji Paper Co.,Ltd.)	20	0	1	40	0	◎
				1'	55	3	◎
				3	40	0	◎

Note)

GS-16: Polyethylene terephthalate film

PP-Type PT, PP-Type R, BO-2400, E 200C: Polypropylene film

NF-13: Polyethylene film

◎: Excellent - A protecting film was removed from a photosensitive resin layer smoothly and easily.

○: Good - A protecting film was removed from a photosensitive resin layer relatively smoothly and easily.

It is apparent from Table 2 that the generation of air voids causing breakage of wire and appearance of defective pattern can be suppressed by using, as the protecting film (C), a film in which the number of fish eyes having a diameter (ϕ) of at least 80 μm does not exceed 5/m².

INDUSTRIAL APPLICABILITY

The photosensitive film of this invention reduces the number of air voids generated which cause occurrence of defective pattern and breakage of wire, and therefore it is quite useful for improvement of product yield in the metallic precision fabrications.

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CLAIMS

1. A photosensitive film which comprises a support film (A), a photosensitive resin composition-containing photosensitive resin layer (B) formed on said support film (A), and a protecting film (C) stuck onto said photosensitive resin layer (B), wherein the number of fish eyes having a diameter of at least 80 μm included in said protecting film (C) does not exceed 5 fish eyes/ m^2 and said photosensitive resin composition-containing photosensitive resin layer (B) has a film thickness of 5 to 30 μm .
2. A photosensitive film according to Claim 1, wherein the photosensitive resin composition in said photosensitive resin layer (B) comprises:
 - (a) a binder polymer formed by copolymerizing acrylic acid or methacrylic acid and alkyl esters thereof as constituent monomers,
 - (b) a monomer having at least one polymerizable ethylenically unsaturated group in the molecule thereof, and
 - (c) a photopolymerization initiator.
3. A photosensitive film according to Claim 1, wherein adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the support film (A) is greater than adhesive strength between the photosensitive resin composition-containing photosensitive resin layer (B) and the protecting film (C).
4. A photosensitive film according to Claim 3, wherein said protecting film is a polypropylene film.

5. A photosensitive film according to Claim 1, wherein said photosensitive film is for use in metal etching process.

6. A photosensitive film according to Claim 1, wherein said photosensitive resin layer has a viscosity of 15 to 50 MPa·s at 30°C.

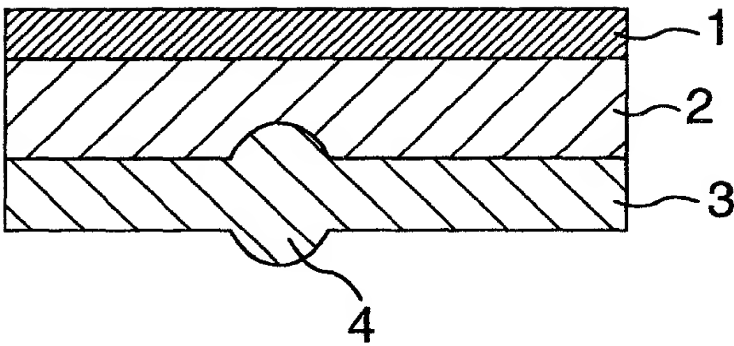
7. A photosensitive film according to Claim 1, wherein said protecting film has a thickness of 5 to 50 μm .

8. A photosensitive film according to Claim 2, wherein said binder polymer (a) contains a carboxyl group-containing monomer in an amount of 12 to 40% by weight based on the total amount of the monomers, has a weight-average molecular weight of 20,000 to 300,000, and is used in an amount of 40 to 80 parts by weight, said monomer (b) is used in an amount of 20 to 60 parts by weight and said photopolymerization initiator (c) is used in an amount of 0.1 to 20 parts by weight, based on 100 parts by weight of the total amounts of (a) and (b).

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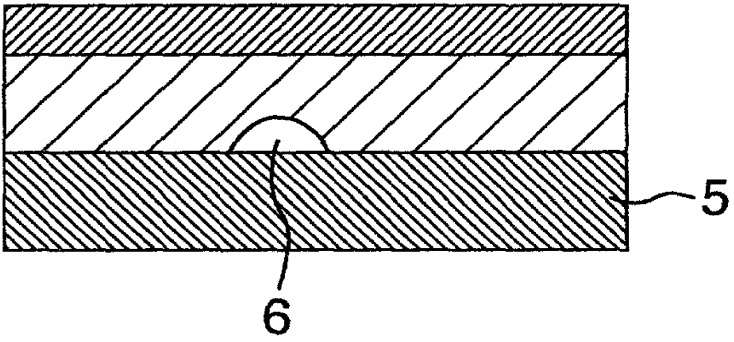
FIG.1A



LAMINATION

↓

FIG.1B



COMBINED DECLARATION AND POWER OF ATTORNEY

(宣誓書及び委任状)

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

"PHOTOSENSITIVE FILM"

the specification of which: (check one) ☐ is attached hereto.

☒ was filed on September 17, 1998
as Application Serial No. PCT/JP98/04184
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended, by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me which is material to patentability in accordance with Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date earlier than that of the application(s) on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
<u>09-254816</u> (Number)	<u>Japan</u> (Country)	<u>19 Sep., 1997</u> (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code, 120 of any United States application(s) or PCT international application(s) designating the United States of America that is/are listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in that/those prior application(s) in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status) (patented, pending, abandoned)
_____ (Application Serial No.)	_____ (Filing Date)	_____ (Status) (patented, pending, abandoned)

(Continued on Page 2)

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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